

3rd Call for Papers

2006 Track on Bond Graph Modelling

Part of the

20th European Conference on Modelling and Simulation (ECMS 2006)

May 28 – 31, 2006

Sankt Augustin, Germany

Extended Submission Deadline: February 10, 2006

Invitation:

You are kindly invited to submit a paper to the 2006 track on Bond Graph Modelling to be held in Sankt Augustin, a small town in the vicinity of the former capital of Germany, Bonn, as part of the 20th European Conference on Modelling and Simulation (ECMS 2006). This track is to address, to explore and to exchange information on the state-of-the-art of *Bond Graph Modelling Methodology* with regard to theory, applications in academia and in industry, and on Bond Graph related software. Participation of researchers, practitioners, teaching staff, students and all those interested in Bond Graph related topics is highly welcome.

Topics:

Bond Graphs are a graphical description formalism that is particularly suited for the concurrent design of multidisciplinary engineering systems with mechanical, electrical, hydraulic or pneumatic components including interactions of physical effects from various energy domains. That is, the methodology is especially useful for modelling mechatronic systems. Accordingly, topics of this track include (but are not limited to):

- Bond Graph Theory (e.g., for Analysis, for Control, for Diagnosis, ...)
- Advanced Bond Graph Methodology
- Bond Graphs and Block Diagrams
- Computer Graphics and Bond Graph Modelling
- Control Systems
- Mechatronic Systems
- Mechanical Systems and Robotics
- Electrical and Power Systems
- Process Engineering (Chemical Processes, Fluid Power Systems)
- Software and Tools
- Industrial Applications of the Methodology

